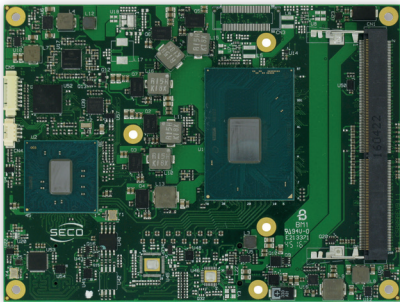




SOM-COMe-BT6-SKL/KL

COM Express® Basic Type 6 with Intel® 6th and 7th generation Core™ / Xeon® (Codename: Skylake and Kaby Lake) CPUs

When high graphics and Hyper-threading matter



HIGHLIGHTS



CPU

Intel® 6th and 7th generation Core™ / Xeon® CPUs



CONNECTIVITY

4x USB 3.0; 8x USB 2.0; 8x PCI-e x1 Gen3;
PEG x16 Gen3



GRAPHICS

Intel® HD Graphics 530 / P530/630/P630



MEMORY

2 x DDR4 So-DIMM slots



MAIN FIELDS OF APPLICATION



Coffee &
Vending



Medical



Digital Signage



Energy &
Utilities

FEATURES

Processor	Intel® Core™ i3-6102E , Dual Core @ 1.9GHz, 3MB Cache, 25W TDP Intel® Core™ i3-6100E , Dual Core @ 2.7GHz, 3MB Cache, 35W TDP Intel® Core™ i5-6442EQ , Quad Core @ 1.9GHz (2.7GHz in Turbo Boost), 6MB Cache, 25W TDP Intel® Core™ i5-6440EQ , Quad Core @ 2.7GHz (3.4GHz in Turbo Boost), 6MB Cache, 45W TDP Intel® Core™ i7-6822EQ , Quad Core @ 2GHz (2.8GHz in Turbo Boost), 8MB Cache, 25W TDP Intel® Core™ i7-6820EQ , Quad Core @ 2.8GHz (3.5GHz in Turbo Boost), 8MB Cache, 45W TDP Intel® Xeon® E3-1505M V5 , Quad Core @ 2.8GHz (3.7GHz in Turbo Boost), 8MB Cache, 45W TDP Intel® Xeon® E3-1515M V5 , Quad Core @ 2.8 GHz, 8MB Cache, 45W TDP (ECC supported), GT4E LINE (D0) with OPC (A0)	Max Thread	8 (HT not available with 6th Generation Core™ i5 and 7th Generation Core™ i3/i5 Processors)
	Intel® Core i3-7102E , Dual core @ 2.10 GHz (3M Cache, 2.10 GHz) FCBGA1440 CPU + GPU - 25W TDP (ECC supported) Intel® Core™ i3-7100E, Dual Core @ 2.9GHz, 3MB Cache, 35W TDP Intel® Core i5-7442EQ , Quad core @ 2.90 GHz (6M Cache, up to 2.90 GHz) FCBGA1440 CPU + GPU - 25W TDP (ECC no supported) Intel® Core i5-7440EQ , Quad Core @ 2.90GHz (up to 3.60 GHz), 6MB Cache, 45W TDP Intel® Core™ i7-7820EQ , Quad Core @ 3.0GHz (3.7GHz in Turbo Boost), 8MB Cache, 45W TDP Intel® Xeon® E3-1505L V6 , Quad core @ 2.20 GHz (8M Cache, 2.20 GHz) FCBGA1440 CPU + GPU - 25W TDP (ECC supported) Intel® Xeon® E3-1505M V6 , Quad Core @ 3.0GHz (4.0GHz in Turbo Boost), 8MB Cache, 45W TDP	Chipset	SkyLake Platform: Intel® QM170, HM170 or CM236 PCH KabyLake Platform: Intel® QM175 or CM238 PCH
Max Cores	4	Memory	Up to two DDR4 SO-DIMM Slots supporting DDR4-2133 (DDR4-2400 for 7th Generation processors) Memory ECC DDR4 memory modules supported only with Xeon® and Core™ i3 processors combined with CM236 / CM238 PCH
		Graphics	Intel® HD Graphics 530 (6th Generation Core™ processors), P530 (6th Generation Xeon® processors) Intel® HD Graphics 630 (7th Generation Core™ processors), P630 (7th Generation Xeon® processors) Up to 3 independent displays supported DirectX® 12.1, OpenGL 4.4, and OpenCL 2.0 support HW accelerated video decode MPEG2, VC1 / WMV9, AVC / H.264, VP8, JPEG / MJPEG, HEVC / H.265, VP9 HW accelerated video encode MPEG2, AVC / H.264, VP8, JPEG / MJPEG, HEVC / H.265, VP9
		Video Interfaces	Up to 3 x Digital Display Interfaces (DDIs), supporting DP 1.2, DVI and HDMI® 1.4 eDP or Single / Dual-Channel 18- / 24- bit LVDS interface or LVDS + VGA interface PCI-express Graphics (PEG) Gen3 x16
		Video Resolution	eDP, DP: up to 4096x2304 @60Hz, 24bpp HDMI®: up to 4096x2160 @60Hz, 24bpp LVDS, VGA: up to 1920 x 1200 @60Hz
		Mass Storage	4 x SATA Gen3 Channels
		Networking	Gigabit Ethernet interface Intel® I219-LM GbE Controller

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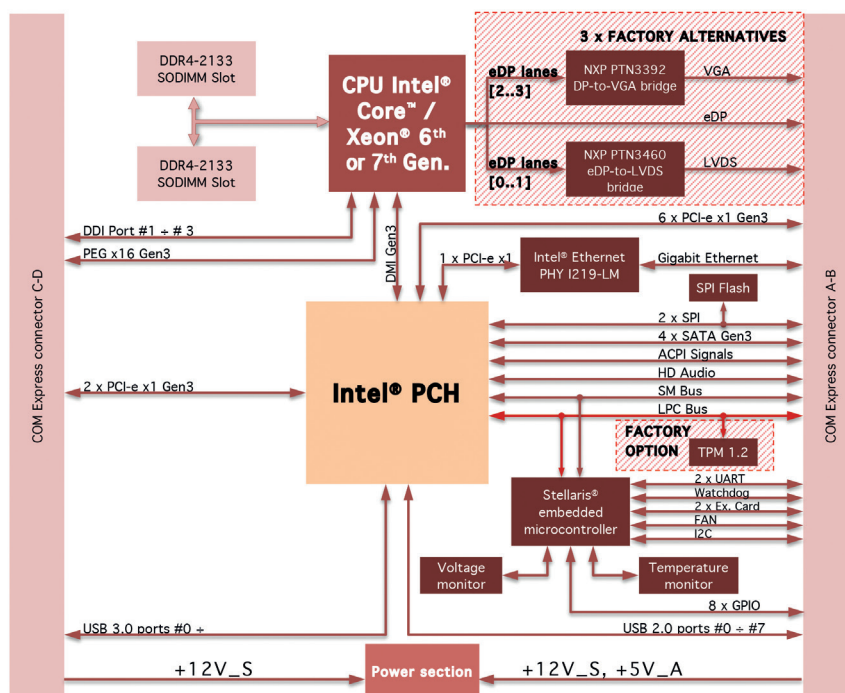
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FEATURES

USB	4 x USB 3.0 Host ports 8 x USB 2.0 Host ports	Operating System	Microsoft® Windows 7 (only for Skylake) Microsoft® Windows 10 Linux
PCI-e	8 x PCI-e x1 Gen3 lanes	Operating Temperature*	0°C ÷ +60°C (Commercial version) -40°C / +70°C (Extended Temperature Range)
Audio	HD Audio Interface	Dimensions	125 x 95 mm (Com Express® Basic Form factor, Type 6 pinout)
Serial Ports	2 x UARTs		
Other Interfaces	2 x SPI, I2C, SM Bus, LPC Bus, 2 x Express Card, FAN management Optional TPM 1.2 LID# / SLEEP# / PWRBTN#, Watchdog 4x GPI, 4 x GPO		
Power Supply	+12V _{DC} ± 10% and +5V _{SB} (optional)		

*Measured at any point of SECO standard heatspreader for this product, during any and all times (including start-up). Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider application-specific cooling solutions for the final system to keep the heatspreader temperature in the range indicated.

BLOCK DIAGRAM



Streamline and expedite your edge computing implementations

EDGEHOG OS

A flexible operating system that adapts to your needs, thanks to the customization tool and Docker support. Reliability and security are built-in through a dual-partition system and native integration with Exein's robust AI-based protection.

DATA ORCHESTRATION

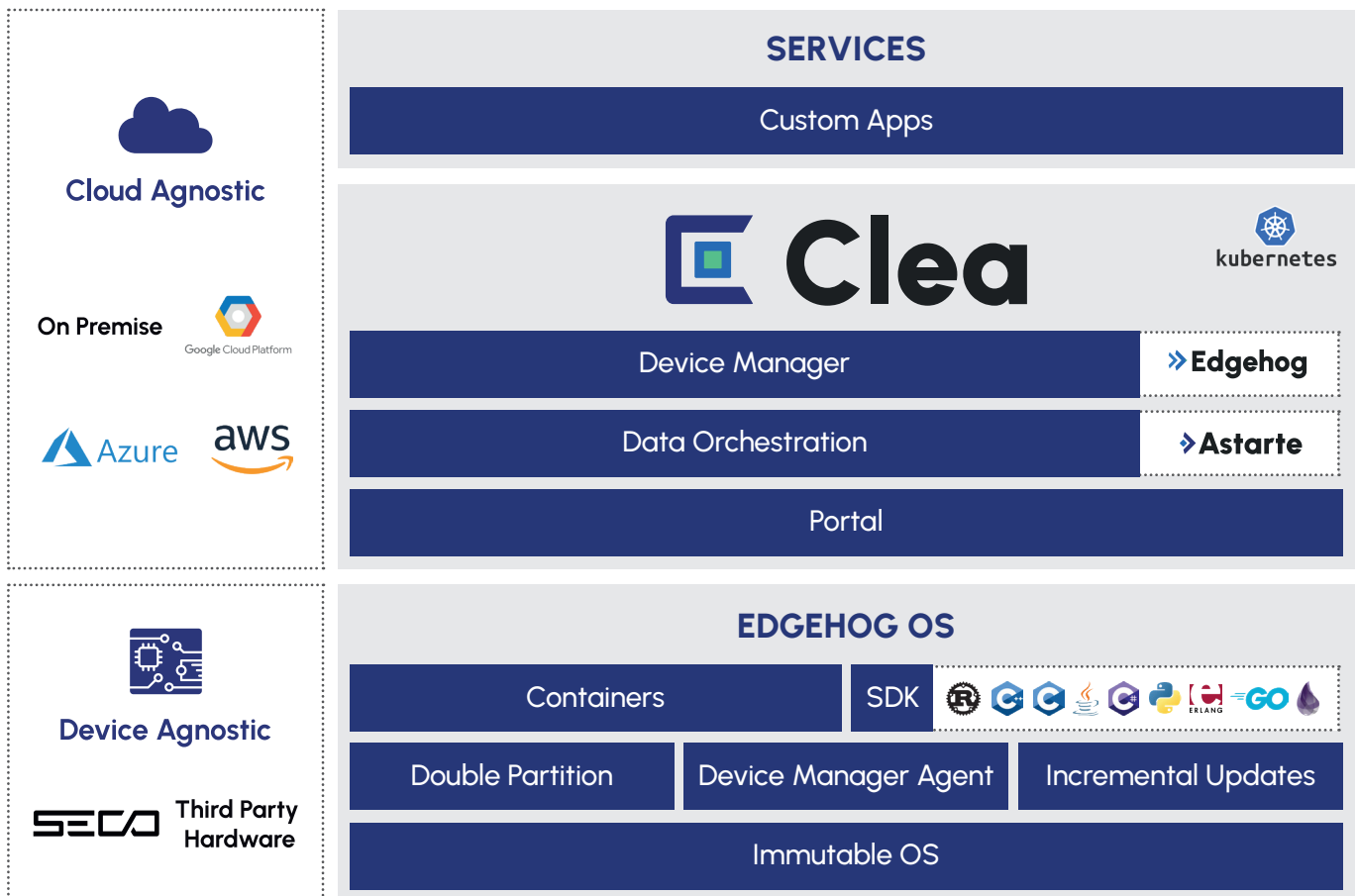
Integrate third-party services, simplify data flows and analysis, and enhance business efficiency by enabling easy and fast utilization of AI.

DEVICE MANAGER

Update, configure, and manage remote devices. Optimize time and costs to maximize operational efficiency and security without the need for costly field interventions.

PORTAL

Analyze data from remote devices, customize the user experience with applications tailored to user needs, and manage user rights, company access, and tenant privileges.



Scan to know more about our solution

EDGEHOG OS



CLEA DOCS

